

ELECTRONIC SEMICONDUCTOR DEVICE HAVING A THERMAL SPREADER

ABSTRACT OF THE DISCLOSURE

The electronic device is formed in a die including a body of semiconductor material having a first face covered by a covering structure and a second face. An integral thermal spreader of metal is grown galvanically on the second face during the manufacture of a wafer, prior to cutting into dice. The covering structure comprises a passivation region and a protective region of opaque polyimide; the protective region and the passivation region are opened above the contact pads for the passage of leads.

D:\NrPortbl\iManage\WENDYT\182429_1.DOC\VI